



SOT1360-1

plastic thermal enhanced extremely thin quad flat package;
no leads; 20 terminals; body 3.5 x 5.5 x 0.85 mm

9 June 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HVSON
Package type industry code	HVSON20
Package style descriptive code	HVSON (thermal enhanced very thin small outline; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	6-7-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.4	-	5.5	5.6	mm
E	package width	3.4	-	3.5	3.6	mm
A	seated height	0.8	-	0.85	1	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	20	-	

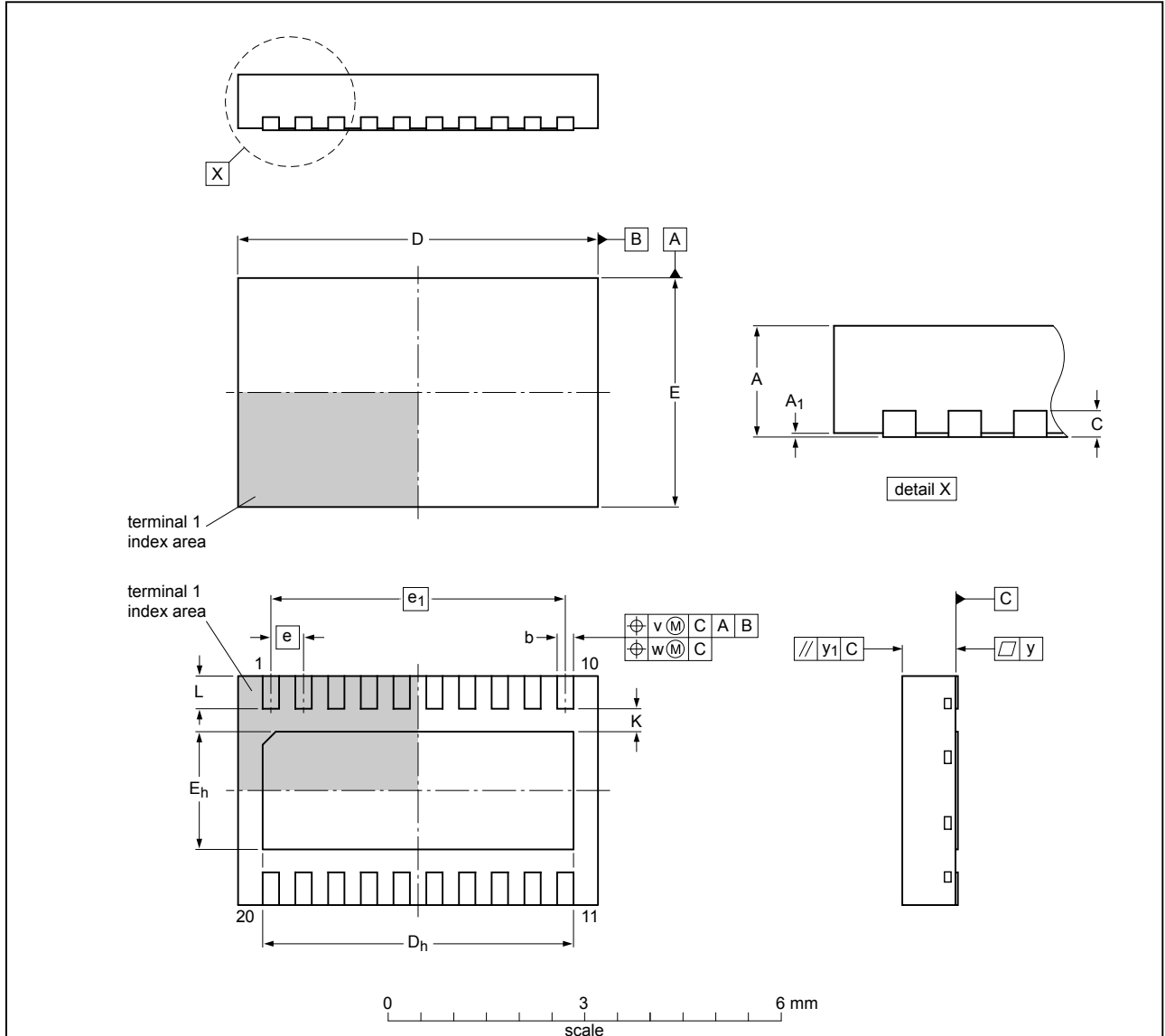


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2. Package outline

HVSON20: plastic thermal enhanced extremely thin quad flat package; no leads; 20 terminals; body 3.5 x 5.5 x 0.85 mm

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Dimensions

Unit	A ⁽¹⁾	A ₁	b	C	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	e ₁	K	L	v	w	y	y ₁
max	1.00	0.05	0.30		5.6	4.85	3.6	1.85			0.40	0.55				
nom	0.85	0.03	0.25	0.2	5.5	4.80	3.5	1.80	0.5	4.5	0.35	0.50	0.1	0.05	0.05	0.1
min	0.80	0.00	0.20		5.4	4.75	3.4	1.75			0.30	0.45				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sov1360-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1360-1		MO-240			-15-05-13- 15-07-06

Fig. 1. Package outline HVSON20 (SOT1360-1)

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3. Legal information

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